

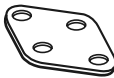


Fig.	Device Type	Dimensions - Inch (mm)							Digi-Key Part No.	Price Each				Bergquist Part No.
		A	B	C	D	E	F	G		1	10	50	100	
8	CPU	.63 (16.00)	.63 (16.00)	—	—	—	—	—	BER133-ND	.52	.47	.42	.38	CPU 63X.63
		1.375 (34.93)	1.375 (34.93)	—	—	—	—	—	BER135-ND	.86	.78	.70	.62	CPU 1.375X1.375
	Bridge Rect.	1.00 (25.40)	1.00 (25.40)	.187 (4.75)	—	—	—	—	BER142-ND	.46	.42	.37	.33	Q3-48
		1.25 (31.75)	1.25 (31.75)	.200 (5.08)	—	—	—	—	BER144-ND	.49	.44	.39	.35	Q3-46
9	TO-220 Tubes	.433 (11.00)	.985 (25.02)	—	—	—	—	—	BER145-ND	1.44	1.29	1.15	1.02	K10-46
		.532 (13.50)	.985 (25.02)	—	—	—	—	—	BER156-ND	.73	.66	.59	.52	SPT400-12-11-25
10	TO-5	.360 (9.14)	.200 (5.08)	.040 (1.02)	—	—	—	—	BER157-ND	.89	.80	.72	.64	SPT400-12-13.5-25
		—	—	—	—	—	—	—	BER213-ND*	.46	.41	.37	.33	7403-09FR-09
<b>"Hi-Flow™" Single Side Adhesive Backed Pads (Phase Change)</b>														
1	TO-3	1.65 (41.91)	1.14 (28.96)	.140 (3.56)	.093 (2.36)	1.187 (30.15)	.430 (10.92)	—	BER166-ND	.28	.25	.23	.20	HF115TAAC-05
3	TO-220	.750 (19.05)	.500 (12.70)	.187 (4.75)	.147 (3.73)	—	—	—	BER167-ND	.10	.09	.08	.07	HF115TAAC-54
3	TO-220	.750 (19.05)	.500 (12.70)	.187 (4.75)	.125 (3.18)	—	—	—	BER168-ND	.10	.09	.08	.07	HF115TAAC-58
3	TO-218	.860 (21.84)	.740 (18.80)	.200 (5.08)	.160 (4.06)	—	—	—	BER169-ND	.12	.10	.09	.08	HF115TAAC-90
5	SIP	1.450 (36.83)	.830 (21.08)	.612 (15.54)	.245 (6.22)	.960 (24.38)	.170 (4.32)	.120 (3.05)	BER170-ND	.14	.13	.11	.10	HF115TAAC-105
<b>"SP900" Single Side Adhesive Backed Pads (Low Mounting Pressure)</b>														
1	TO-3	1.65 (41.91)	1.14 (28.96)	.140 (3.56)	.093 (2.36)	1.187 (30.15)	.430 (10.92)	—	BER181-ND	1.14	1.03	.92	.81	SP900EAC-05
3	TO-220	.750 (19.05)	.500 (12.70)	.187 (4.75)	.147 (3.73)	—	—	—	BER182-ND	.74	.67	.60	.53	SP900EAC-54
3	TO-220	.750 (19.05)	.500 (12.70)	.187 (4.75)	.125 (3.18)	—	—	—	BER183-ND	.74	.67	.60	.53	SP900EAC-58
<b>"Bond Ply™ 100" Double Sided Thermal Tape</b>														
Double Sided Adhesive Thermal Pad, .005" (.127) Thick, 11" x 12" (27.94 x 30.48cm) Square Sheet									BER246-ND	41.44	36.98	33.15	29.33	BOND PLY 105 11x12"
Double Sided Adhesive Thermal Pad, .008" (.203) Thick, 10" (25.4cm) Square Sheet									BER159-ND	50.99	45.51	40.80	36.09	BOND PLY 108 10x10"
Double Sided Adhesive Thermal Pad, .011" (.279) Thick, 10" (25.4cm) Square Sheet									BER160-ND	63.77	56.90	51.02	45.13	BOND PLY 111 10x10"
<b>"Gap Pad™ 1500" Thermal Gap Filling Material</b>														
High Thermally Conductive Pad, .020" (.508) Thick, 4" (10.16cm) Square Sheet									BER161-ND	9.98	8.91	7.99	7.07	.020 GP 1500 4" x 4"
High Thermally Conductive Pad, .040" (1.02) Thick, 4" (10.16cm) Square Sheet									BER162-ND	14.33	12.79	11.47	10.15	.040 GP 1500 4" x 4"
High Thermally Conductive Pad, .060" (1.52) Thick, 4" (10.16cm) Square Sheet									BER163-ND	16.45	14.68	13.16	11.64	.060 GP 1500 4" x 4"
High Thermally Conductive Pad, .080" (2.03) Thick, 4" (10.16cm) Square Sheet									BER164-ND	19.44	17.35	15.55	13.76	.080 GP 1500 4" x 4"
High Thermally Conductive Pad, .125" (3.18) Thick, 4" (10.16cm) Square Sheet									BER165-ND	26.39	23.55	21.12	18.68	.125 GP 1500 4" x 4"
High Thermally Conductive Pad, .040" (1.02) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER227-ND	99.03	88.37	79.23	70.09	.040 GP 1500 8" x 16"
High Thermally Conductive Pad, .060" (1.52) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER228-ND	96.85	86.42	77.48	68.54	.060 GP 1500 8" x 16"
High Thermally Conductive Pad, .080" (2.03) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER229-ND	110.92	98.98	88.74	78.50	.080 GP 1500 8" x 16"
High Thermally Conductive Pad, .125" (3.18) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER230-ND	189.31	168.93	151.45	133.98	.125 GP 1500 8" x 16"
<b>"Gap Pad™ 1500R" Thermal Gap Filling Material</b>														
High Thermally Conductive Pad, .010" (.254) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER231-ND	54.21	48.38	43.37	38.37	GP1500R 10 MIL 8" x 16"
High Thermally Conductive Pad, .015" (.381) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER232-ND	66.40	59.25	53.12	46.99	GP1500R 15 MIL 8" x 16"
High Thermally Conductive Pad, .020" (.508) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER233-ND	72.96	65.11	58.37	51.64	GP1500R 20 MIL 8" x 16"
<b>"Gap Pad™ VO Ultra Soft" Thermal Gap Filling Material</b>														
High Thermally Conductive Pad, .020" (.508) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER222-ND	72.05	64.30	57.65	51.00	.020 GP US 8" x 16"
High Thermally Conductive Pad, .040" (1.02) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER223-ND	90.61	80.86	72.49	64.13	.040 GP US 8" x 16"
High Thermally Conductive Pad, .060" (1.52) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER224-ND	101.66	90.72	81.33	71.95	.060 GP US 8" x 16"
High Thermally Conductive Pad, .080" (2.03) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER225-ND	116.48	103.94	93.19	82.44	.080 GP US 8" x 16"
High Thermally Conductive Pad, .125" (3.18) Thick, 8" x 16" (20.32 x 40.64cm) Sheet									BER226-ND	193.38	172.55	154.70	136.85	.125 GP US 8" x 16"

\* Made of SP400 material

C

**KEYSTONE**



**MICA Insulators for Transistor Mounting**

These precision stamped MICA insulators provide good thermal conductivity (.009 watts per square inch per °C per inch in thickness). Excellent thermal resistance 1100°F (593°C). Dielectric constant of 7 at 1000KHz. Specifications: .003" (.08mm) thick MICA ± .001" (± .003mm)

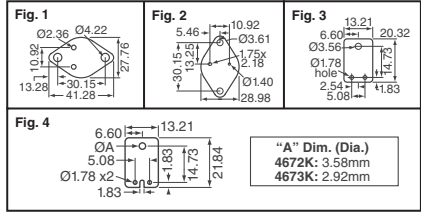
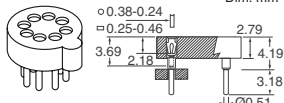


Fig.	Digi-Key Part No.	10	100	500	1,000	Keystone Part No.
1	4651K-ND	1.19	10.45	35.50	48.10	4651
2	4662K-ND	1.30	11.25	37.25	52.65	4662
3	4671K-ND	1.26	10.45	35.50	25.45	4671
4	4672K-ND	1.10	10.45	35.50	19.70	4672
4	4673K-ND	1.10	10.45	35.50	19.70	4673

**MILL-MAX**

**Transistor Sockets**

Plating: Sleeve (Pin): 200µ" Sn/Pb (RoHS Compliant: 200µ" Sn); Contact (Clip): 30µ" Au



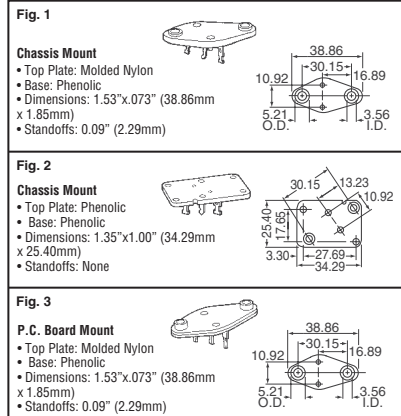
No. of Pins	Digi-Key Part No.	1	10	100	Mill-Max Part No.
<b>TO-5 Package</b>					
3	ED2150-ND	1.29	1.10	.90	917-93-103-41-005000
3	ED90273-ND	1.77	1.50	1.23	917-43-103-41-005000
4	ED2151-ND	1.39	1.18	.97	917-93-104-41-005000
4	ED90274-ND	1.87	1.59	1.30	917-43-104-41-005000
8	ED2152-ND	1.80	1.53	1.25	917-93-108-41-005000
8	ED90275-ND	2.30	1.95	1.60	917-43-108-41-005000
<b>TO-100 Package</b>					
8	ED2153-ND	1.80	1.53	1.25	917-93-208-41-005000
8	ED90276-ND	2.30	1.95	1.60	917-43-208-41-005000
10	ED2154-ND	2.64	2.24	1.83	917-93-210-41-005000
10	ED90277-ND	2.78	2.36	1.93	917-43-210-41-005000

• RoHS Compliant

**KEYSTONE**



**TO-3 Power Transistor Sockets**



**Transistor Mounting Hardware**

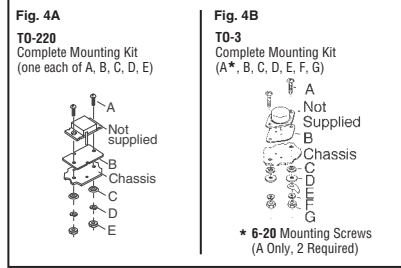


Fig.	Digi-Key Part No.	1	10	100	Keystone Part No.
1	4601K-ND	2.29	2.16	2.07	4601
2	4606K-ND	1.95	1.84	1.60	4606
3	4600K-ND	2.04	1.93	1.75	4600
4A	4724K-ND	1.95	1.81	1.60	4724
4B	4725K-ND	1.95	1.81	1.60	4725
4B	4706K-ND*	2.68/20	25.40/200		4706

**ASAHI RUBBER INC.**



**Heat Sink Pads**

Asahi Rubber offers an excellent product for applications requiring a thermal solution. The ART Series is a thermally conductive silicone gel that can be cut as required.

Features: • Color: Gray • Dimensions: 11.81" x 8.46" (300mm x 215mm) • Thickness range: 0.3 mm to 2.0 mm • Operating Temperature Range: -60°C - 200°C

Thickness Inch (mm)	Digi-Key Part No.	1	10	50	Asahi Part No.
.01 (0.3)	509-1000-ND	48.12	44.11	39.30	ART03
.02 (0.5)	509-1001-ND	53.01	48.60	43.30	ART05
.04 (1.0)	509-1002-ND	76.59	70.21	62.55	ART10
.06 (1.5)	509-1003-ND	98.19	90.01	80.19	ART15
.08 (2.0)	509-1004-ND	120.12	110.11	98.10	ART20

**molex**



**TO-220 Solder Tail Transistor Sockets**

P.C. Board Mount: .100" (2.54mm) center. These three circuit transistor sockets are preassembled and ready for soldering to a P.C. Board. The proven double cantilever design eliminates circuit failure due to thermal expansion and/or mechanical tolerances.

Linear movement of the transistor leads in the socket does not affect contact reliability.

Material: Tin-Plated Brass, 94V-2 Rated Nylon

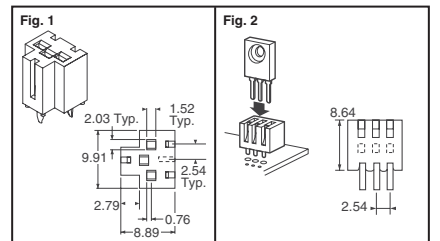


Fig.	Digi-Key Part No.	1	10	100	Molex Part No.
1	WM2550-ND	1.63	1.45	.97	09-48-3031
2	WM2551-ND	2.13	1.89	1.26	10-18-2031

More Product Available Online: [www.digkey.com](http://www.digkey.com)